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Amendment under 37 C.F.R. §1.312

IN THE ABSTRACT:

Please amend the Abstract of the Disclosure on page 14 as follows:

The package of the present invention includes a chip located on a substrate with a signal transferring device electrically connected between them. Solder balls connect the substrate and thus electrically connect the substrate to external circuits. Molding compound is covered to protect the chip and signal transferring means. The heat-slug is capped over the molding compound through a conductive glue. All The entire area of the upper surface of the heat-slug is exposed to the ambient to improve the ~~capability of~~ spreading ability to spread heat.